

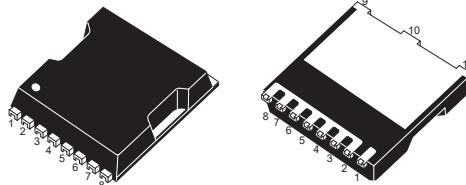
## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 100V, 296A,  $R_{DS(ON)}$  typ = 1.6mΩ @ $V_{GS}$  = 10V
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- RoHS compliant.
- TOLL package.

### Applications

- DC/DC Converter



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous@ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$I_D$	296	A
		209	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	1184	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above 25°C	$P_D$	333	W
		2.2	W/°C
Single Pulsed Avalanche Energy <sup>d</sup>	$E_{AS}$	720	mJ
Single Pulsed Avalanche Current <sup>d</sup>	$I_{AS}$	60	A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 175	°C

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.45	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	60	°C/W



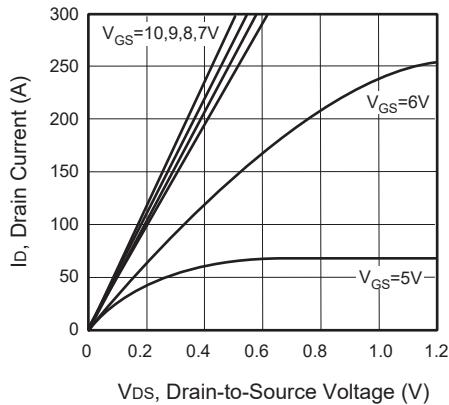
# CEL29100

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

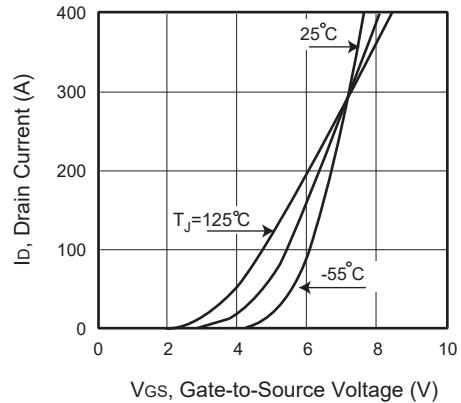
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2	4		V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		1.6	1.9	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 100\text{A}$		1.7	2.0	$\text{m}\Omega$
Gate input resistance	$R_g$	f=1MHz,open Drain		2.1		$\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		4570		pF
Output Capacitance	$C_{\text{oss}}$			1250		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			70		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 10\Omega$		50		ns
Turn-On Rise Time	$t_r$			88		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			167		ns
Turn-Off Fall Time	$t_f$			122		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		155		nC
Gate-Source Charge	$Q_{\text{gs}}$			29.5		nC
Gate-Drain Charge	$Q_{\text{gd}}$			57		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_s$				277	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 20\text{A}$			1.2	V
Reverse Recovery Time	$T_{\text{rr}}$	$I_F = 20\text{A}, dI/dt = 500\text{A}/\mu\text{s}$		80		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			625		nC

Notes :

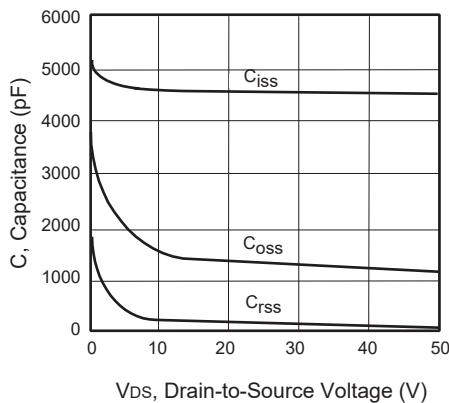
- a.Repetitive Rating : Pulse width limited by maximum junction temperature
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- c.Guaranteed by design, not subject to production testing.
- d.L = 0.4mH,  $I_{\text{AS}} = 60\text{A}$ ,  $V_{\text{DD}} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$



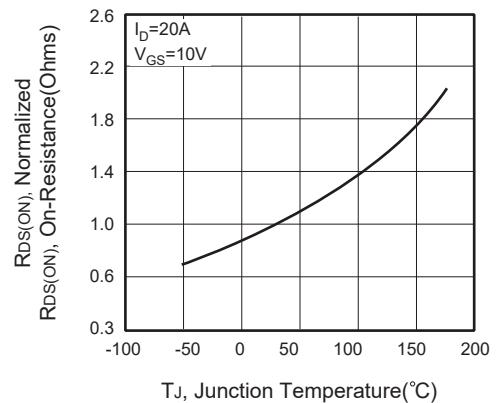
**Figure 1. Output Characteristics**



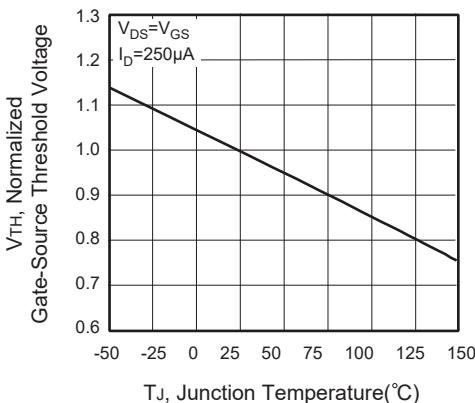
**Figure 2. Transfer Characteristics**



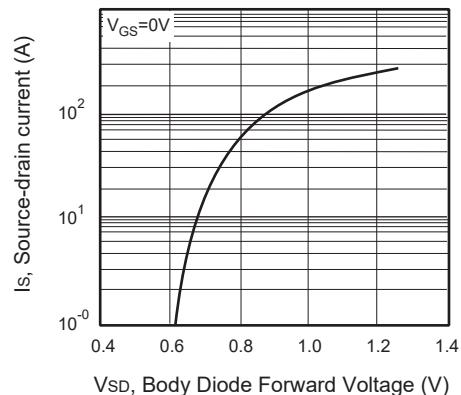
**Figure 3. Capacitance**



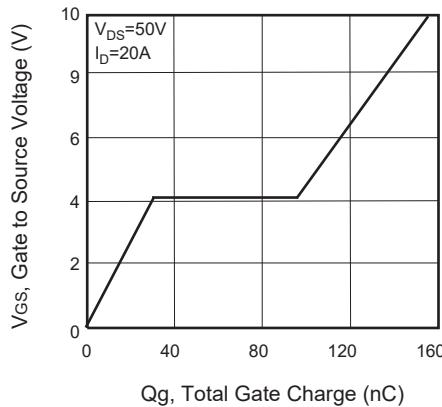
**Figure 4. On-Resistance Variation with Temperature**



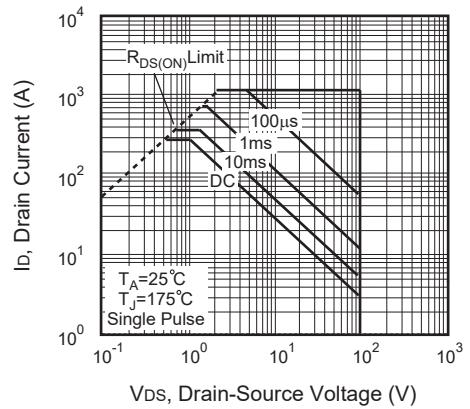
**Figure 5. Gate Threshold Variation with Temperature**



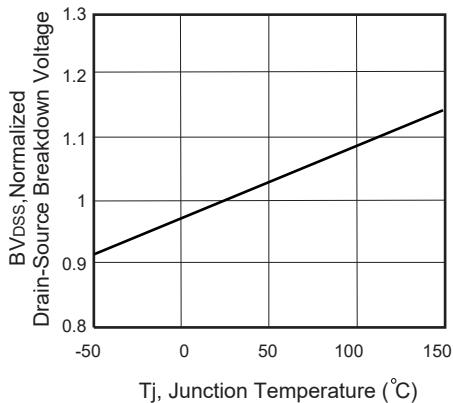
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



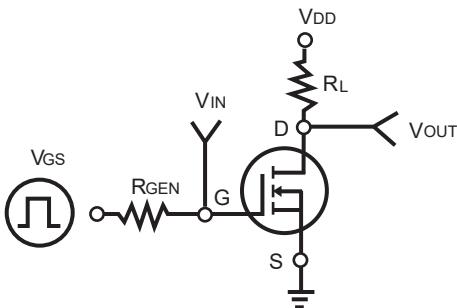
**Figure 7. Gate Charge**



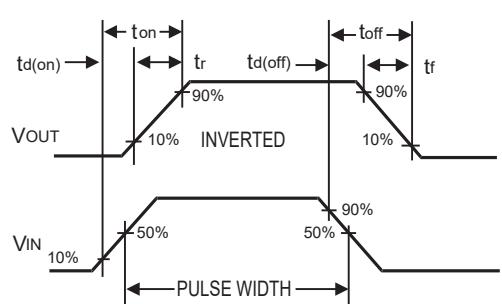
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**

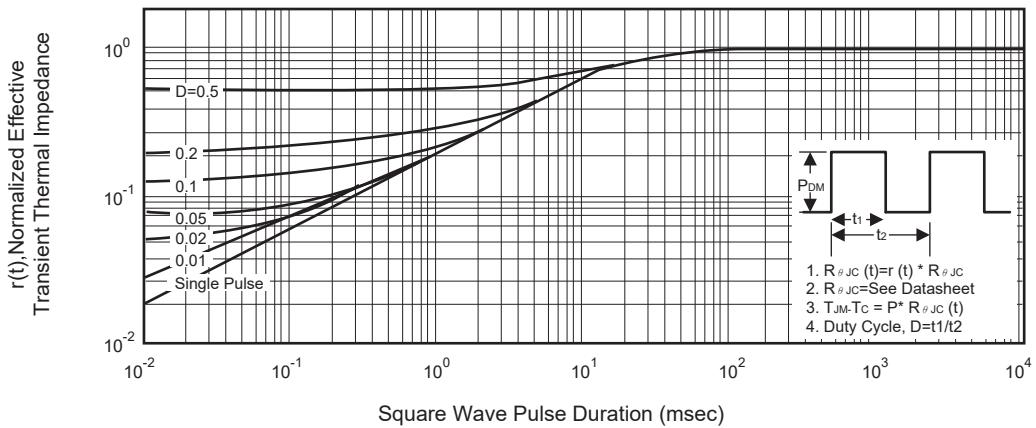
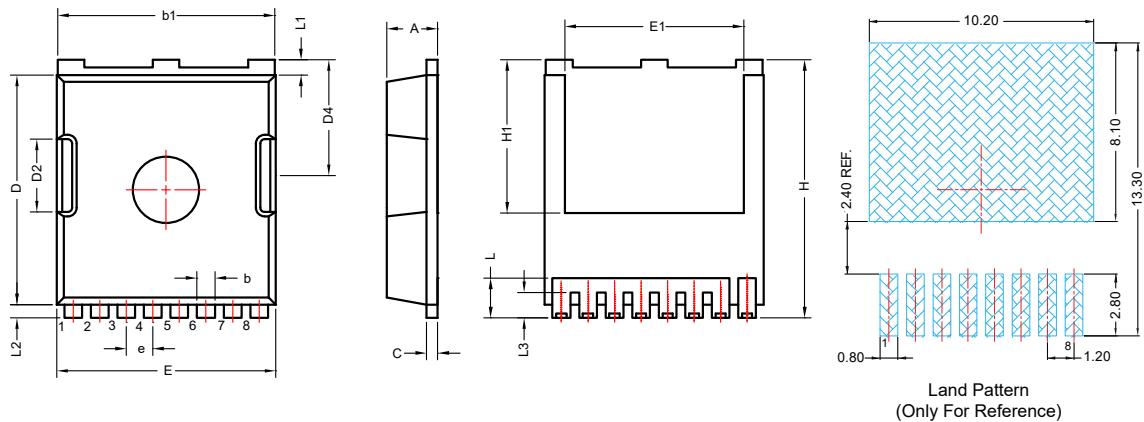


Figure 12. Normalized Thermal Transient Impedance Curve



# CEL29100

## TOLL 產品外觀尺寸圖 (Product Outline Dimension)



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.150	2.450	0.085	0.096
b	0.700	0.900	0.028	0.035
b1	9.650	9.950	0.380	0.392
c	0.400	0.600	0.016	0.024
D	10.180	10.580	0.401	0.417
D2	3.150	3.450	0.124	0.136
D4	4.400	4.700	0.173	0.185
E	9.700	10.100	0.382	0.398
E1	7.950	8.250	0.313	0.325
e	1.20BSC		0.047BSC	
H	11.480	11.880	0.452	0.468
H1	6.800	7.100	0.268	0.280
L	1.500	2.100	0.059	0.083
L1	0.500	0.900	0.020	0.035
L2	0.500	0.720	0.020	0.028
L3	1.000	1.300	0.039	0.051